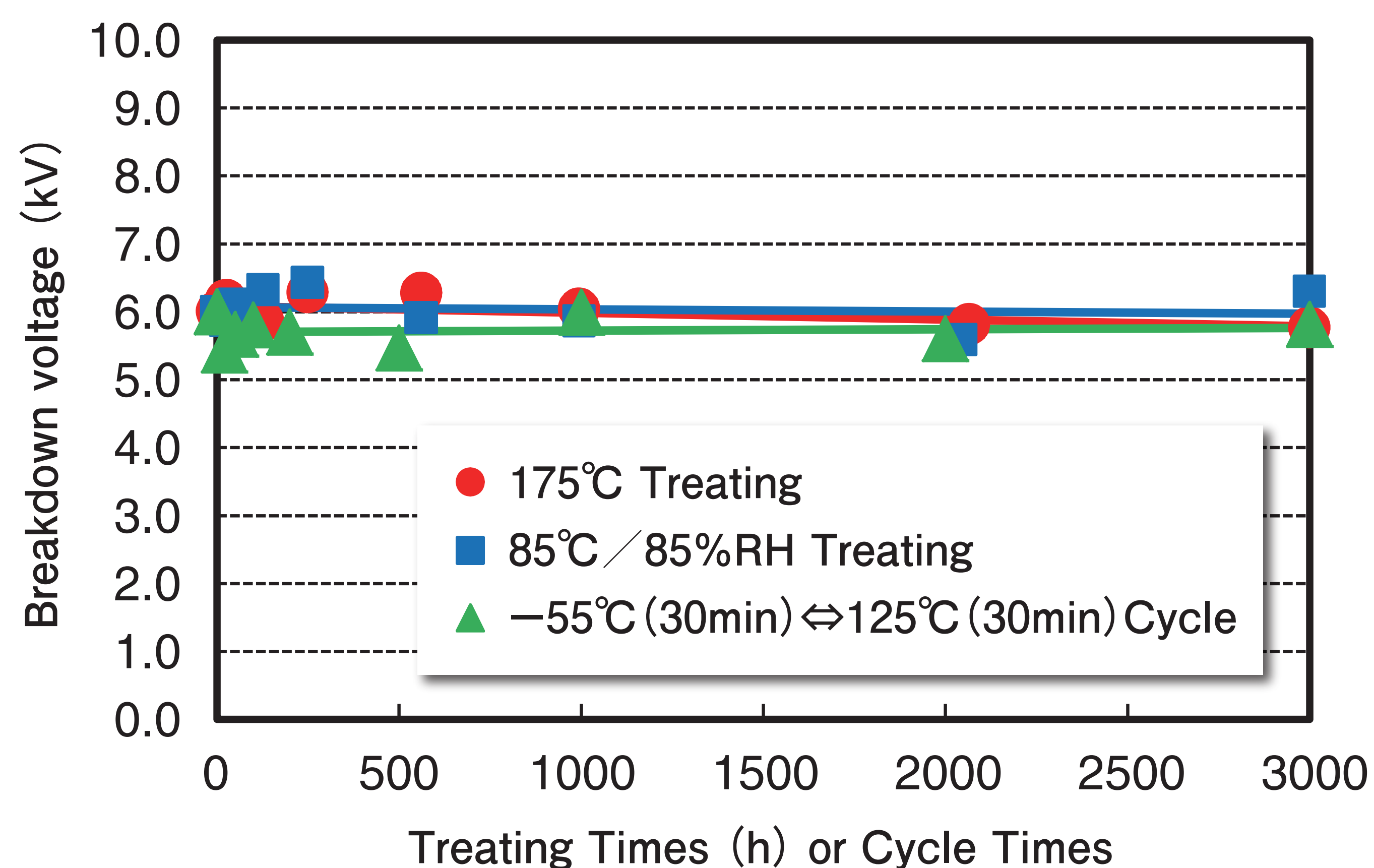
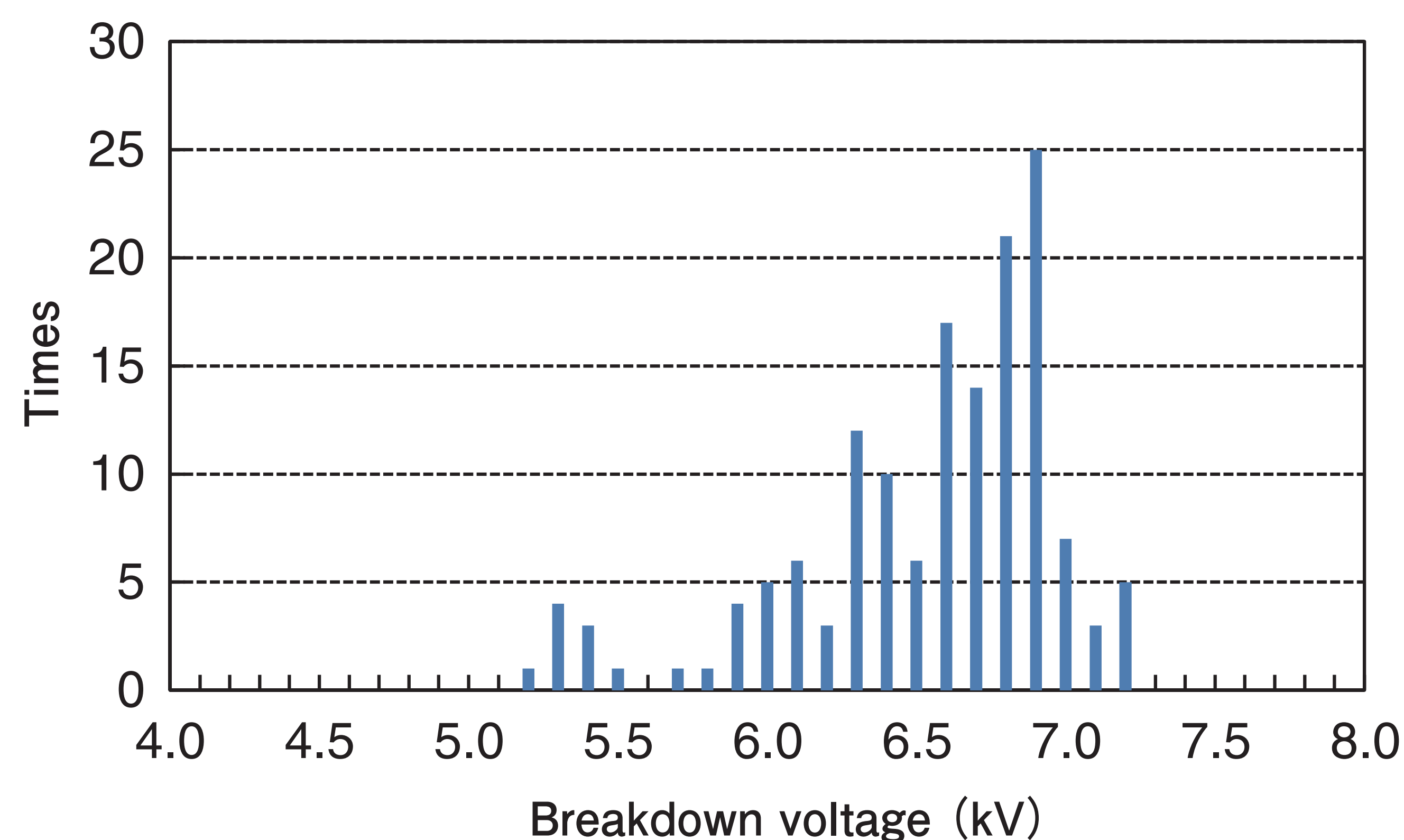


Solution !**Thermal
Conductivity*****3W/mK******Inhibit
Solder Crack*****Features**

- Thermal conductivity = **3W/mK**
- Insulation layer has flexibility after heat curing
(Young's modules(RT) is less one — tenth than FR-4)
- 7303 series has excellent long term reliability

Applications

- Metal PCB requiring to inhibit solder crack
- Metal PCB requiring stress relaxation (Automotive engine room)

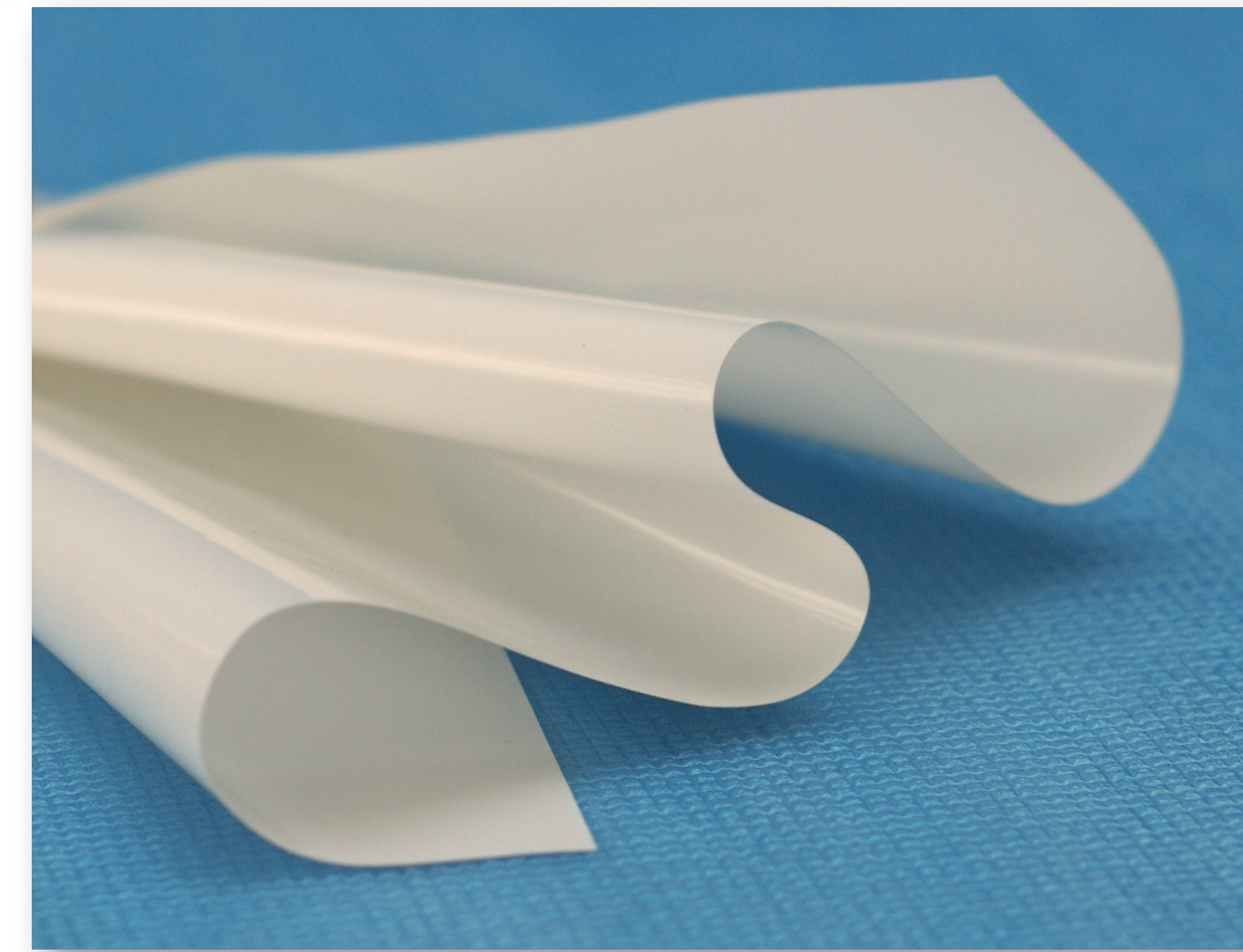
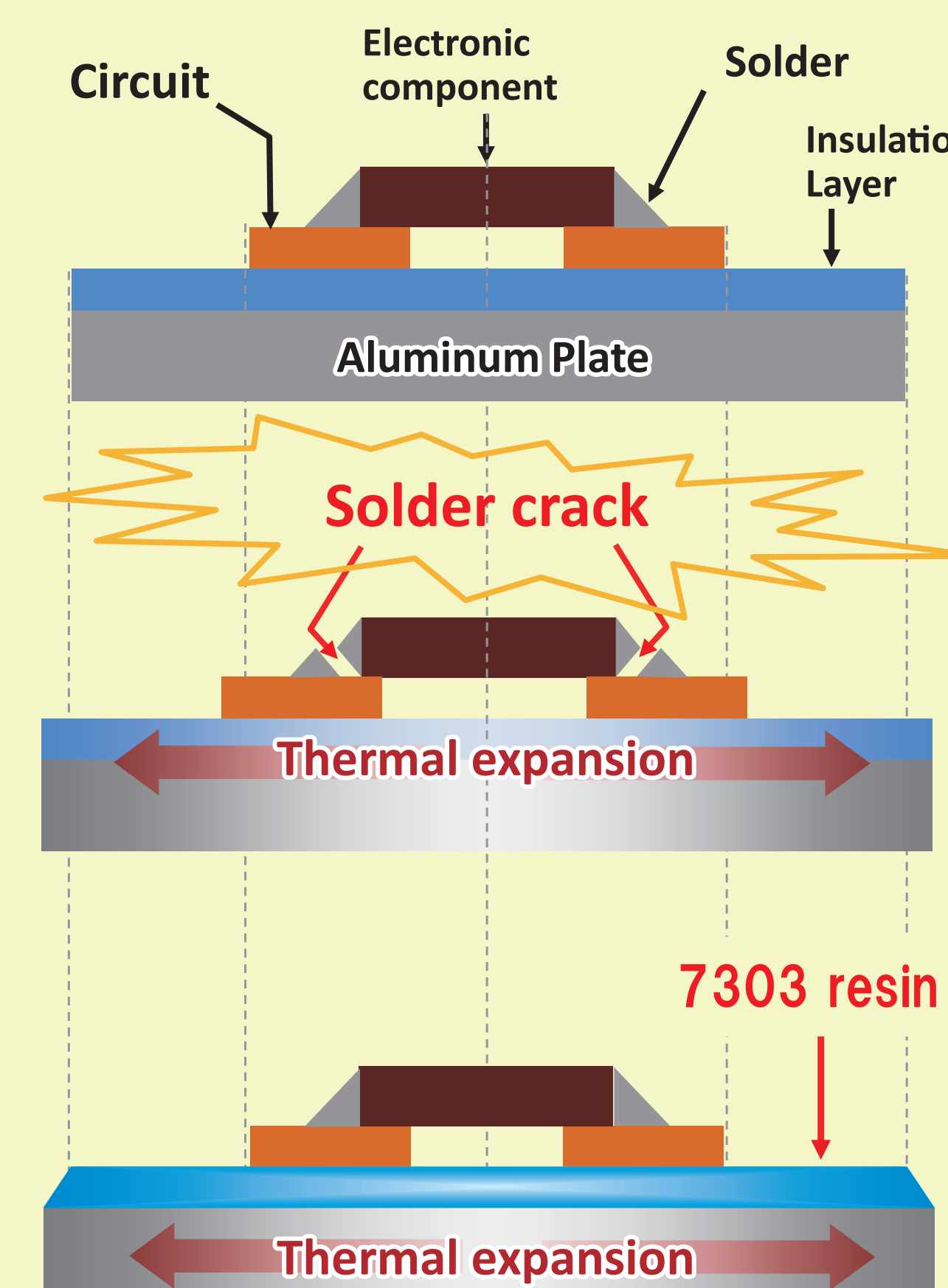
Breakdown voltage (AC)

High thermal conductive & Low elastic PWB material

AD-7303 / AC-7303

Bonding sheet

Aluminum-base CCL

Insulation layer
After heat curing**Solder crack image and solution**

7303 resin has superior flexibility after heat curing.
AC-7303 is aluminum base material with 7303 resin.
Solder crack doesn't happen easily even in extreme difference of temperature such as engine room of automotive.

Copper Peel Strength